

# **Embedded Die Packaging Technology Market by Platform (Embedded Die in IC Package Substrate, Embedded Die in Rigid Board, and Embedded Die in Flexible Board) and Industry Vertical (Consumer Electronics, IT & Telecommunications, Automotive, Healthcare, and Others): Global Opportunity Analysis and Industry Forecast, 2017-2023**

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## **Abstracts**

The global embedded die packaging technology was valued at \$26 million in 2016, and is projected to reach \$68 million by 2023, growing at a CAGR of 14.8% from 2017 to 2023. Embedded die packaging technology is a native 3D-compatible packaging solution, offering nearly 70% size reduction in system in package (SiP) solution. The advantages of this technology include miniaturization, improved electrical & thermal performance, heterogeneous integration, prospect for reduction in cost, and efficient logistics for OEM. In addition, it offers flexible system integration, fast turnaround for custom design, high robustness, and enhanced reliability of the package.

Embedded die packaging technology was anticipated to grow rapidly with the development in smartphones; however, this technology showed limited success in smartphones due to competition from faster developing Flip Chip and especially WLP platforms. However, in automotive, healthcare, aerospace, and industrial sectors, numerous products utilizing embedded die packaging technology are expected to arrive in the market during the next four to five years.

The factors that drive the market are impending need for circuit miniaturization in microelectronic devices, increase in number of portable electronic devices, rise in application in healthcare and automotive devices, and advantages over other advanced packaging technologies. However, requirement of high cost of these chips restrains the market growth restrains the market growth. Moreover, rapid adoption of IoT globally is

expected to present new opportunities in the market.

The global embedded die packaging technology market is segmented based on platform, industry vertical, and geography. Based on platform, it is classified into embedded die in IC package substrate, embedded die in rigid board, and embedded die in flexible board. Based on industry vertical, it is categorized into consumer electronics, IT & telecommunication, automotive, healthcare, and others. Geographically, it is analyzed across North America (U.S., Mexico, and Canada), Europe (UK, Germany, France, and rest of Europe), Asia-Pacific (China, Japan, Taiwan, South Korea, and rest of Asia-Pacific), and LAMEA (Latin America, Middle East, and Africa).

The major companies profiled in the report include Amkor Technology, Taiwan Semiconductor Manufacturing Company, ASE Group, AT & S, General Electric, Infineon, Fujikura, MicroSemi, TDK-Epcos, and Schweizer.

## **KEY BENEFITS FOR STAKEHOLDERS**

The study provides an in-depth analysis of the global embedded die packaging technology market to elucidate the prominent investment pockets from 2016 to 2023.

Current trends and future estimations are outlined to determine the overall market scenario.

The report provides information about the key drivers, restraints, and opportunities with a detailed impact analysis.

## **KEY MARKET SEGMENTS**

### **BY PLATFORM**

Embedded Die in IC Package Substrate

Embedded Die in Rigid Board

Embedded Die in Flexible Board

### **BY INDUSTRY VERTICAL**

Consumer Electronics

IT & Telecommunication

Automotive

Healthcare

Others

## BY GEOGRAPHY

North America

U.S.

Mexico

Canada

Europe

UK

Germany

France

Rest of Europe

Asia-Pacific

China

Japan

Taiwan

South Korea

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

### Key players

Amkor Technology

Taiwan Semiconductor Manufacturing Company

ASE Group

AT & S

General Electric

Infineon

Fujikura

MicroSemi

TDK-Epcos

Schweizer

## Contents

### **CHAPTER 1 INTRODUCTION**

- 1.1. REPORT DESCRIPTION
- 1.2. KEY BENEFITS FOR STAKEHOLDERS
- 1.3. KEY MARKET SEGMENTS
- 1.4. RESEARCH METHODOLOGY
  - 1.4.1. Secondary research
  - 1.4.2. Primary research
  - 1.4.3. Analyst tools and models

### **CHAPTER 2 EXECUTIVE SUMMARY**

- 2.1. CXO PERSPECTIVE

### **CHAPTER 3 MARKET OVERVIEW**

- 3.1. MARKET DEFINITION AND SCOPE
- 3.2. KEY FINDINGS
  - 3.2.1. Top impacting factors
  - 3.2.2. Top winning strategies
  - 3.2.3. Top investment pockets
- 3.3. PORTERS FIVE FORCES ANALYSIS
  - 3.3.1. Porters five forces analysis
- 3.4. MARKET DYNAMICS
  - 3.4.1. Drivers
  - 3.4.2. Restraint
  - 3.4.3. Opportunity

### **CHAPTER 4 EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY PLATFORM TYPE**

- 4.1. OVERVIEW
  - 4.1.1. Market size and forecast
- 4.2. EMBEDDED DIE IN IC PACKAGE SUBSTRATE
  - 4.2.1. Introduction
  - 4.2.2. Key market trends, growth factors, and opportunities
  - 4.2.3. Market size and forecast

#### 4.3. EMBEDDED DIE IN RIGID BOARD

4.3.1. Introduction

4.3.2. Key market trends, growth factors, and opportunities

4.3.3. Market size and forecast

#### 4.4. EMBEDDED DIE IN FLEXIBLE BOARD

4.4.1. Introduction

4.4.2. Key market trends, growth factors, and opportunities

4.4.3. Market size and forecast

### **CHAPTER 5 EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL**

#### 5.1. OVERVIEW

5.1.1. Market size and forecast

#### 5.2. CONSUMER ELECTRONICS

5.2.1. Introduction

5.2.2. Key market trends, growth factors, and opportunities

5.2.3. Market size and forecast

#### 5.3. IT & TELECOMMUNICATION

5.3.1. Introduction

5.3.2. Key market trends, growth factors, and opportunities

5.3.3. Market size and forecast

#### 5.4. AUTOMOTIVE

5.4.1. Introduction

5.4.2. Key market trends, growth factors, and opportunities

5.4.3. Market size and forecast

#### 5.5. HEALTHCARE

5.5.1. Introduction

5.5.2. Key market trends, growth factors, and opportunities

5.5.3. Market size and forecast

#### 5.6. OTHERS

5.6.1. Introduction

5.6.2. Key market trends, growth factors, and opportunities

5.6.3. Market size and forecast

### **CHAPTER 6 EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY**

#### 6.1. OVERVIEW

- 6.1.1. Market size and forecast
- 6.2. NORTH AMERICA
  - 6.2.1. Introduction
  - 6.2.2. Key market trends, growth factors, and opportunities
  - 6.2.3. Market size and forecast
  - 6.2.4. U.S.
    - 6.2.4.1. Market size and forecast
  - 6.2.5. Canada
    - 6.2.5.1. Market size and forecast
  - 6.2.6. Mexico
    - 6.2.6.1. Market size and forecast
- 6.3. EUROPE
  - 6.3.1. Introduction
  - 6.3.2. Key market trends, growth factors, and opportunities
  - 6.3.3. Market size and forecast
  - 6.3.4. UK
    - 6.3.4.1. Market size and forecast
  - 6.3.5. Germany
    - 6.3.5.1. Market size and forecast
  - 6.3.6. France
    - 6.3.6.1. Market size and forecast
  - 6.3.7. Rest of Europe
    - 6.3.7.1. Market size and forecast
- 6.4. ASIA-PACIFIC
  - 6.4.1. Introduction
  - 6.4.2. Key market trends, growth factors and opportunities
  - 6.4.3. Market size and forecast
  - 6.4.4. China
    - 6.4.4.1. Market size and forecast
  - 6.4.5. Japan
    - 6.4.5.1. Market size and forecast
  - 6.4.6. Taiwan
    - 6.4.6.1. Market size and forecast
  - 6.4.7. South Korea
    - 6.4.7.1. Market size and forecast
  - 6.4.8. Rest of Asia-Pacific
    - 6.4.8.1. Market size and forecast
- 6.5. LAMEA
  - 6.5.1. Introduction

6.5.2. Key market trends, growth factors, and opportunities

6.5.3. Market size and forecast

6.5.4. Latin America

6.5.4.1. Market size and forecast

6.5.5. Middle East

6.5.5.1. Market size and forecast

6.5.6. Africa

6.5.6.1. Market size and forecast

## **CHAPTER 7 RELATED INDUSTRY INSIGHTS**

### **7.1. WORLD 3D SEMICONDUCTOR PACKAGING MARKET**

7.1.1. Executive Summary

### **7.2. WORLD FLIP CHIP MARKET**

7.2.1. Executive Summary

## **CHAPTER 8 COMPANY PROFILES**

### **8.1. AMKOR TECHNOLOGY**

8.1.1. Company overview

8.1.2. Operating business segments

8.1.3. Business performance

8.1.4. Key strategic moves and developments

### **8.2. ASE GROUP**

8.2.1. Company overview

8.2.2. Operating business segments

8.2.3. Business performance

8.2.4. Key strategic moves and developments

### **8.3. AT & S**

8.3.1. Company overview

8.3.2. Operating business segments

8.3.3. Business performance

8.3.4. Key strategic moves and developments

### **8.4. FUJIKURA LTD.**

8.4.1. Company overview

8.4.2. Operating business segments

8.4.3. Business performance

8.4.4. Key strategic moves and developments

### **8.5. GENERAL ELECTRIC**



- 8.5.1. Company overview
- 8.5.2. Operating business segments
- 8.5.3. Business performance
- 8.5.4. Key strategic moves and developments
- 8.6. INFINEON TECHNOLOGIES AS
  - 8.6.1. Company overview
  - 8.6.2. Operating business segments
  - 8.6.3. Business performance
  - 8.6.4. Key strategic moves and developments
- 8.7. MICROSEMI CORPORATION
  - 8.7.1. Company overview
  - 8.7.2. Operating business segments
  - 8.7.3. Business performance
  - 8.7.4. Key strategic moves and developments
- 8.8. SCHWEIZER ELECTRONICS AG
  - 8.8.1. Company overview
  - 8.8.2. Operating business segments
  - 8.8.3. Business performance
  - 8.8.4. Key strategic moves and developments
- 8.9. TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED
  - 8.9.1. Company overview
  - 8.9.2. Operating business segments
  - 8.9.3. Business performance
  - 8.9.4. Key strategic moves and developments
- 8.10. TDK CORPORATION
  - 8.10.1. Company overview
  - 8.10.2. Operating business segments
  - 8.10.3. Business performance
  - 8.10.4. Key strategic moves and developments

## List Of Tables

### LIST OF TABLES

TABLE 1. GLOBAL EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY PLATFORM TYPE, 2016-2023 (\$MILLION)

TABLE 2. EMBEDDED DIE IN IC PACKAGE SUBSTRATE MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 3. EMBEDDED DIE IN RIGID BOARD MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 4. EMBEDDED DIE IN FLEXIBLE BOARD MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 5. GLOBAL EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL, 2016-2023 (\$MILLION)

TABLE 6. CONSUMER ELECTRONICS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 7. IT & TELECOMMUNICATION EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 8. AUTOMOTIVE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 9. HEALTHCARE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 10. OTHERS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 11. EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY GEOGRAPHY, 2016-2023 (\$MILLION)

TABLE 12. NORTH AMERICA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY TECHNOLOGY, 2016-2023 (\$MILLION)

TABLE 13. NORTH AMERICA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL, 2016-2023 (\$MILLION)

TABLE 14. NORTH AMERICA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY COUNTRY, 2016-2023 (\$MILLION)

TABLE 15. EUROPE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY TYPE, 2016-2023 (\$MILLION)

TABLE 16. EUROPE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL, 2016-2023 (\$MILLION)

TABLE 17. EUROPE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY COUNTRY, 2016-2023 (\$MILLION)

TABLE 18. ASIA-PACIFIC EMBEDDED DIE PACKAGING TECHNOLOGY MARKET,

BY TECHNOLOGY, 2016-2023 (\$MILLION)

TABLE 19. ASIA-PACIFIC EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL, 2016-2023 (\$MILLION)

TABLE 20. ASIA-PACIFIC EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY COUNTRY, 2016-2023 (\$MILLION)

TABLE 21. LAMEA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY TECHNOLOGY, 2016-2023 (\$MILLION)

TABLE 22. LAMEA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY INDUSTRY VERTICAL, 2016-2023 (\$MILLION)

TABLE 23. LAMEA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, BY COUNTRY, 2016-2023 (\$MILLION)

TABLE 24. AMKOR TECHNOLOGY: COMPANY SNAPSHOT

TABLE 25. AMKOR TECHNOLOGY: OPERATING SEGMENTS

TABLE 26. ASE GROUP: COMPANY SNAPSHOT

TABLE 27. ASE GROUP: OPERATING SEGMENTS

TABLE 28. AT & S: COMPANY SNAPSHOT

TABLE 29. AT & S: OPERATING SEGMENTS

TABLE 30. FUJIKURA LTD.: COMPANY SNAPSHOT

TABLE 31. FUJIKURA LTD.: OPERATING SEGMENTS

TABLE 32. GENERAL ELECTRIC: COMPANY SNAPSHOT

TABLE 33. GENERAL ELECTRIC: OPERATING SEGMENTS

TABLE 34. INFINEON TECHNOLOGIES AG: COMPANY SNAPSHOT

TABLE 35. INFINEON TECHNOLOGIES AG: OPERATING SEGMENTS

TABLE 36. MICROSEMI CORPORATION: COMPANY SNAPSHOT

TABLE 37. MICROSEMI CORPORATION: OPERATING SEGMENTS

TABLE 38. SCHWEIZER ELECTRONICS AG: COMPANY SNAPSHOT

TABLE 39. SCHWEIZER ELECTRONICS AG: OPERATING SEGMENTS

TABLE 40. TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED: COMPANY SNAPSHOT

TABLE 41. TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED: OPERATING SEGMENTS

TABLE 42. TDK CORPORATION: COMPANY SNAPSHOT

TABLE 43. TDK CORPORATION: OPERATING SEGMENTS

## List Of Figures

### LIST OF FIGURES

FIGURE 1. MARKET SEGMENTATION

FIGURE 2. TOP IMPACTING FACTORS

FIGURE 3. TOP WINNING STRATEGIES: PERCENTAGE DISTRIBUTION  
(2013-2016)

FIGURE 4. TOP INVESTMENT POCKETS IN GLOBAL EMBEDDED DIE PACKAGING  
TECHNOLOGY MARKET, BY INDUSTRY VERTICAL

FIGURE 5. BARGAINING POWER OF SUPPLIERS

FIGURE 6. BARGAINING POWER OF BUYERS

FIGURE 7. THREAT OF SUBSTITUTES

FIGURE 8. THREAT OF NEW ENTRANTS

FIGURE 9. INTENSITY OF COMPETITIVE RIVALRY

FIGURE 10. COMPARATIVE REGIONAL SHARE ANALYSIS OF EMBEDDED DIE IN  
IC PACKAGE SUBSTRATE MARKET, 2016 & 2023 (%)

FIGURE 11. GLOBAL EMBEDDED DIE IN IC PACKAGE SUBSTRATE MARKET,  
2016-2023 (\$MILLION)

FIGURE 12. GLOBAL EMBEDDED DIE IN IC PACKAGE SUBSTRATE MARKET  
ANALYSIS, 2016 & 2023

FIGURE 13. COMPARATIVE REGIONAL SHARE ANALYSIS OF EMBEDDED DIE IN  
RIGID BOARD MARKET, 2016 & 2023 (%)

FIGURE 14. GLOBAL EMBEDDED DIE IN RIGID BOARD MARKET, 2016-2023  
(\$MILLION)

FIGURE 15. GLOBAL EMBEDDED DIE IN RIGID BOARD MARKET ANALYSIS, 2016  
& 2023

FIGURE 16. COMPARATIVE REGIONAL SHARE ANALYSIS OF EMBEDDED DIE IN  
FLEXIBLE BOARD MARKET, 2016 & 2023 (%)

FIGURE 17. GLOBAL EMBEDDED DIE IN FLEXIBLE BOARD MARKET, 2016-2023  
(\$MILLION)

FIGURE 18. GLOBAL EMBEDDED DIE IN FLEXIBLE BOARD MARKET ANALYSIS,  
2016 & 2023

FIGURE 19. COMPARATIVE REGIONAL SHARE ANALYSIS OF CONSUMER  
ELECTRONICS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016 &  
2023 (%)

FIGURE 20. GLOBAL CONSUMER ELECTRONICS EMBEDDED DIE PACKAGING  
TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 21. GLOBAL CONSUMER ELECTRONICS EMBEDDED DIE PACKAGING

TECHNOLOGY MARKET ANALYSIS, 2016 & 2023

FIGURE 22. COMPARATIVE REGIONAL SHARE ANALYSIS OF IT & TELECOMMUNICATION EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016 & 2023 (%)

FIGURE 23. GLOBAL IT & TELECOMMUNICATION EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 24. GLOBAL IT & TELECOMMUNICATION EMBEDDED DIE PACKAGING TECHNOLOGY MARKET ANALYSIS, 2016 & 2023

FIGURE 25. COMPARATIVE REGIONAL SHARE ANALYSIS OF AUTOMOTIVE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016 & 2023 (%)

FIGURE 26. GLOBAL AUTOMOTIVE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 27. GLOBAL AUTOMOTIVE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET ANALYSIS, 2016 & 2023

FIGURE 28. COMPARATIVE REGIONAL SHARE ANALYSIS OF HEALTHCARE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016 & 2023 (%)

FIGURE 29. GLOBAL HEALTHCARE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 30. GLOBAL HEALTHCARE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET ANALYSIS, 2016 & 2023

FIGURE 31. COMPARATIVE REGIONAL SHARE ANALYSIS OF OTHERS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016 & 2023 (%)

FIGURE 32. GLOBAL OTHERS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 33. GLOBAL OTHERS EMBEDDED DIE PACKAGING TECHNOLOGY MARKET ANALYSIS, 2016 & 2023

FIGURE 34. U.S. EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 35. CANADA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 36. MEXICO EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 37. UK EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 38. GERMANY EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 39. FRANCE EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 40. REST OF EUROPE EMBEDDED DIE PACKAGING TECHNOLOGY

MARKET, 2016-2023 (\$MILLION)

FIGURE 41. CHINA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 42. JAPAN EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 43. TAIWAN EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 44. SOUTH KOREA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 45. REST OF ASIA-PACIFIC EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 46. LATIN AMERICA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 47. MIDDLE EAST EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 48. AFRICA EMBEDDED DIE PACKAGING TECHNOLOGY MARKET, 2016-2023 (\$MILLION)

FIGURE 49. AMKOR TECHNOLOGY: COMPANY SNAPSHOT

FIGURE 50. ASE GROUP: COMPANY SNAPSHOT

FIGURE 51. AT & S: COMPANY SNAPSHOT

FIGURE 52. FUJIKURA LTD.: COMPANY SNAPSHOT

FIGURE 53. GENERAL ELECTRIC: COMPANY SNAPSHOT

FIGURE 54. INFINEON TECHNOLOGIES AG: COMPANY SNAPSHOT

FIGURE 55. MICROSEMI CORPORATION: COMPANY SNAPSHOT

FIGURE 56. SCHWEIZER ELECTRONICS AG: COMPANY SNAPSHOT

FIGURE 57. TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED: COMPANY SNAPSHOT

FIGURE 58. TDK CORPORATION: COMPANY SNAPSHOT

## I would like to order

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